Docket No.: JCLA31893

Form 1595 (Rev. 09/04) RECORDATION FORM	I COVER SHEET U.S. Department of Commerce Patent and Trademark Office
PATENTS ON	<u>LY</u>
To the Director of the U.S. Patent and Trademark Office: Please re-	cord the attached documents or the new address(es) below.
Name of conveying party(ies):	Name/address of receiving Party(ies):
Names(s) Date of Execution	
Huang, Shih-Fu Jan. 22, 2010	Advanced Semiconductor
Su, Yuan-Chang Jan. 22, 2010	Engineering, Inc.
Hsieh, Chia-Hsiung Jan. 22, 2010	26, Chin 3rd. Rd., 811, Nantze
	Export Processing Zone,
	Kaohsiung, Taiwan, R.O.C.
	_
3. Nature of conveyance: ☒ Assignment	
☐ Merger ☐ Security Agreement ☐Other	
☐ Change of Name ☐ Reassignment	Add'1 name(s)/address(es) of receiving parties
	Attached? ☐ Yes 区 No
4. Application number(s) or patent number(s):	
A. Patent Application No. (s)	B. Patent No. (s)
12/694,539	
Additional numbers attached?	☐ Yes ⊠ No
5. Name and address of party to whom	6. Total No. of applications and patents
Correspondence concerning document should be mailed:	involved:
should be maried.	ONE(1)
J. C. Patents 4, Venture Suite 250	7. Total fee (37 CFR §3.41): <u>\$40.00</u>
Irvine, CA. 92618	☐Authorized to be charge by credit card
Tel: (949) 660-0761	⊠Authorized to be charge to deposit account □Enclosed
Fax: (949) 660-0809	☐None required (government interest not affecting title)
E-mail: jcpi@msn.com	8. Payment Information
·	a. Credit Card Last Numbers Expiration Date
	b. Deposit Account Number 50-0710
atty Docket No.: JCLA31893	Authorized User Name <u>Jiawei Huang</u>
9. Statement and Signature:	
To the best of my knowledge and belief, the for attached copy is a true copy of the original doct	
Jiawei Huang Jame of Person Signing egistration No. 43,330 Signature	Total number of pages including cover sheet, attachments, and documents: 3

PATENT REEL: 023862 FRAME: 0250 ASEK2244 31893-US-PA

ASSIGNMENT

WHEREAS.

1. Huang, Shih-Fu

2. Su, Yuan-Chang

3. Hsieh, Chia-Hsiung

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: FABRICATION METHOD OF CIRCUIT BOARD, CIRCUIT BOARD, AND CHIP PACKAGE STRUCTURE

[] Filed:

Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, Advanced Semiconductor Engineering, Inc. of 26, Chin 3rd. Rd., 811, Nantze Export Processing Zone, Kachslung, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASEK2244 31893-US-PA

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Huang Shih Fa

Date: Jan. 22, 2010

Sole or First Joint Inventor: Huang, Shih-Fu

Signature: Su Ywan Chang

Date: Jan. 22, 2010

Second Joint Inventor (if any): Su, Yuan-Chang

Signature: Auch Lho - Haway

Date: Jan. 22, 2010

Third Joint Inventor (if any): Hsieh, Chia-Hsiung

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CERTIFICATE OF TRANSMISSION

January 27, 2010

Atty Docket No.	:	JCLA31893
Appl. No.	:	12/694,539
Filing Date	:	January, 27, 2010
Pages	:	Cover + 3

BY FACSIMILE ONLY

Fax No.	:	571-273-0140
Attention	:	MAIL STOP Assignment Commissioner for Patents
From	:	Jiawei Huang, Reg. No. 43,330
MESSAGE	:	Enclosed herewith is a Recordation Cover Sheet with Assignment in 3 pages.

Sir:

I hereby certify that this correspondence is being facsimile transmitted to the Patent and Trademark Office on January 27, 2010 at the above indicated fax number.

Sign by

Michelle Chang

Note: This facsimile transmission is intended only for the use of the individual or entity to which it is addressed, and may contain information that is privileged, confidential and exempt from disclosure under applicable law. If the reader is not the intended recipient, or the employee or agent responsible for delivering the message to the intended recipient, you are hereby notified that any dissemination, distribution or copying of this communication is strictly prohibited. If you have received this transmission in error, please kindly notify us immediately, and return the original message to us at the above address. We greatly appreciate your cooperation.

PATENT REEL: 023862 FRAME: 0253

RECORDED: 01/27/2010